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(54) Title: SUBSTRATE LOCATION DETECTION AND ADJUSTMENT

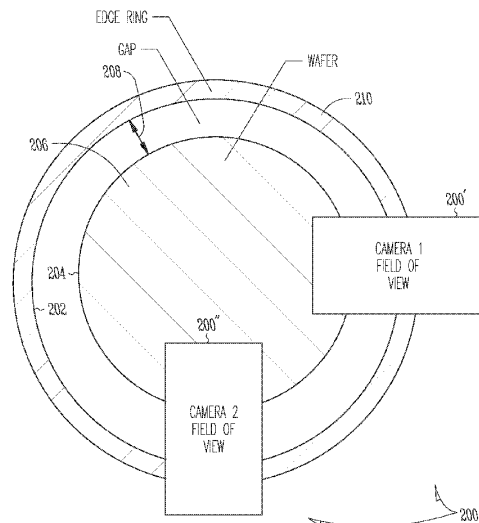


Fig. 2

(57) Abstract: Systems and methods are provided for positioning a wafer in relation to a datum structure. In one example, a system comprises a camera arrangement including at least two cameras, each of the at least two cameras including a field of view when positioned in the camera arrangement, each field of view including a peripheral edge of the wafer and a peripheral edge of the datum structure. A processor receives positional data from each of the at least two cameras and determines, in relation to each field of view, a gap size between the respective peripheral edges of the wafer and the datum location included in the respective field of view. A controller adjusts a position of the wafer relative to the datum structure based on the determined respective gap sizes.

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